

Accepted Manuscript

Antimicrobial finishing of textiles intended for food processing industry by plasma enhanced chemical vapor deposition – Physical vapor deposition of Ag-SiOCH composites coated with AlxOy or SiOCH encapsulation layers

Céline Brunon, Elise Chadeau, Nadia Oulahal, Carol Grossiord, Laurent Dubost, Farida Simon, François Bessueille, Pascal Degraeve, Didier Leonard



PII: S0040-6090(17)30179-7
DOI: doi: [10.1016/j.tsf.2017.03.004](https://doi.org/10.1016/j.tsf.2017.03.004)
Reference: TSF 35852
To appear in: *Thin Solid Films*
Received date: 5 June 2016
Revised date: 24 February 2017
Accepted date: 3 March 2017

Please cite this article as: Céline Brunon, Elise Chadeau, Nadia Oulahal, Carol Grossiord, Laurent Dubost, Farida Simon, François Bessueille, Pascal Degraeve, Didier Leonard, Antimicrobial finishing of textiles intended for food processing industry by plasma enhanced chemical vapor deposition – Physical vapor deposition of Ag-SiOCH composites coated with AlxOy or SiOCH encapsulation layers. The address for the corresponding author was captured as affiliation for all authors. Please check if appropriate. Tsf(2017), doi: [10.1016/j.tsf.2017.03.004](https://doi.org/10.1016/j.tsf.2017.03.004)

This is a PDF file of an unedited manuscript that has been accepted for publication. As a service to our customers we are providing this early version of the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting proof before it is published in its final form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain.

**Antimicrobial finishing of textiles intended for food
processing industry by plasma enhanced chemical vapor
deposition – physical vapor deposition of Ag-SiOCH
composites coated with Al_xO_y or SiOCH encapsulation layers**

Céline BRUNON ^{a,c}, Elise CHADEAU ^b, Nadia OULAHAL ^b, Carol GROSSIORD ^c,
Laurent DUBOST ^d, Farida SIMON ^e, François BESSUEILLE ^a, Pascal DEGRAEVE
^b, Didier LEONARD ^{a,*}

^a Université de Lyon, CNRS, Université Claude Bernard Lyon 1, ENS de Lyon, Institut des Sciences Analytiques, UMR 5280, 5 rue de la Doua, F-69100 VILLEURBANNE, France

^b Univ Lyon, Université Claude Bernard Lyon 1, ISARA Lyon, BioDyMIA (Bioingénierie et Dynamique Microbienne aux Interfaces Alimentaires), Equipe Mixte d'Accueil n°3733, IUT Lyon 1, Technopole Alimentec, rue Henri de Boissieu, F-01000, Bourg en Bresse, France

^c Science et Surface, 64, Chemin des Mouilles, F-69130 Ecully, France

^d HEF, ZI SUD, rue Benoît Fourneyron, F-42166 Andrézieux Bouthéon, France

^e TDV Industrie, 43 rue du Bas des Bois, BP 1217, F-53012 Laval Cedex, France

* Corresponding author. Tel: + 33 437 42 35 54

E-mail address: didier.leonard@univ-lyon1.fr

Download English Version:

<https://daneshyari.com/en/article/5466275>

Download Persian Version:

<https://daneshyari.com/article/5466275>

[Daneshyari.com](https://daneshyari.com)